



MOLD-TEK
Packaging Limited

MTPL/SECT/24/2026-27

Date: July 27, 2026

To The Secretary, Listing Department, BSE Limited, Phiroze Jeejeebhoy Towers, Dalal Street, Fort, Mumbai-400001. Scrip Code: 533080	To The Manager, Listing Department, National Stock Exchange of India Limited, Exchange Plaza, 5 th Floor, Plot No. C/1, G Block, Bandra Kurla Complex, Bandra (E), Mumbai-400051. Symbol: MOLDTKPAC
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Dear Sir/Madam,

Sub: Audio Recording of Conference Call for Investors held on July 27, 2026.

Pursuant to the Regulation 30 of SEBI (Listing Obligations and Disclosure Requirements), Regulations 2015 and further to our letter dated July 22, 2026, please note that the audio recording of the Conference Call for investors held on July 27, 2026, at 4:30 PM (IST), to discuss Q1FY27 results of the Company has been uploaded on our website on the following web-link:

<https://moldteckpackaging.com/pdf/Audio%20Recording%20of%20Q1FY27%20Earnings%20Call.mp3>

This is for your kind information and records.

Thanking you,

Yours faithfully,

For Mold-Tek Packaging Limited

J. Lakshmana Rao
Chairman and Managing Director
DIN: 00649702